

Type number	Package	Package description	Total product weight
74AUP1G885GT	SOT833-1	XSON8	2.60958 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935280767115	17	1	260	30 s	1	240	20 s	3	Ayutthaya, Thailand; Nijmegen, Netherlands; Suzhou, China; Bangkok, Thailand; Seremban, Malaysia	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.10136	100.00000	3.88396
		subTotal		0.10136	100.00000	3.88396
Component	Additive	Non hazardous	Proprietary	0.00100	5.00000	0.03832
	Filler	Aluminium Trioxide (Al2O3)	1344-28-1	0.00800	40.00000	0.30656
	Polymer	Bisphenol-A Bisphenol-A Diglycidyl Ether copolymer	25036-25-3	0.00300	15.00000	0.11496
		Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00200	10.00000	0.07664
		Resin system	Proprietary	0.00600	30.00000	0.22992
subTotal			0.02000	100.00000	0.76640	
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.98836	92.37000	37.87426
		Magnesium (Mg)	7439-95-4	0.00150	0.14000	0.05740
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.03082	2.88000	1.18088
		Silicon (Si)	7440-21-3	0.00663	0.62000	0.25422
	Pure metal layer	Gold (Au)	7440-57-5	0.00043	0.04000	0.01640
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.04055	3.79000	1.55400
		Palladium (Pd)	7440-05-3	0.00171	0.16000	0.06560
subTotal			1.07000	100.00000	41.00276	
Mould Compound	Filler	Silica -amorphous-	7631-86-9	0.27200	20.00000	10.42313
		Silica fused	60676-86-0	0.87720	64.50000	33.61460
	Flame retardant	Metal hydroxide	Proprietary	0.04080	3.00000	1.56347
	Impurity	Silicon Dioxide (SiO2)	14808-60-7	0.00680	0.50000	0.26058
	Pigment	Carbon black	1333-86-4	0.00408	0.30000	0.15635
		Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.02992	2.20000
		Phenolic resin	Proprietary	0.03400	2.50000	1.30289
	Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.09520	7.00000	3.64810	
subTotal				1.36000	100.00000	52.11566
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00000	0.00300	0.00002
		Bismuth (Bi)	7440-69-9	0.00000	0.00100	0.00001
		Copper (Cu)	7440-50-8	0.00000	0.00100	0.00001
		Lead (Pb)	7439-92-1	0.00000	0.00500	0.00004
	Tin solder	Tin (Sn)	7440-31-5	0.02000	99.99000	0.76633
subTotal				0.02000	100.00000	0.76641
Wire	Gold alloy	Gold (Au)	7440-57-5	0.03784	99.00000	1.44996

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
		Palladium (Pd)	7440-05-3	0.00038	1.00000	0.01465
		subTotal		0.03822	100.00000	1.46461

#### Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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